# Specification of Thermoelectric Module TES1-03115

#### **Description**

The 31 couples, 12mmx12mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

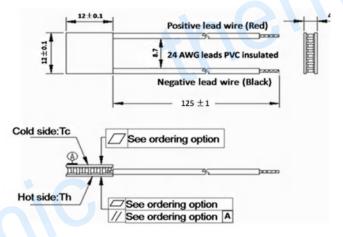
#### **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

#### **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	3.9	4.2	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	1.7	1.7	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	4.2	4.5	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.73	1.86	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

#### Geometric Characteristics Dimensions in millimeters



## **Manufacturing Options**

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)

**B. Sealant:** 

38°C) 1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C) 2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C) 3. EPS: Epoxy sealant

#### C. Ceramics:

#### **D. Ceramics Surface Options:**

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

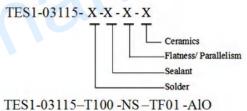
2. Aluminum Nitride (AlN) 2. Metalized

#### **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)
	H (mm)	Parallelism (mm)	Standard/Optional length
TF	0:4.0± 0.1	0: 0.05/0.05	125±1/Specify
TF	1: 4.0± 0.03	1: 0.02 /0.02	125±1/Specify

Eg. TF01: Thickness  $4.0\pm0.1$  (mm) and Flatness 0.02/0.02 (mm)

## Naming for the Module



T100: BiSn(Tmelt=138°C)

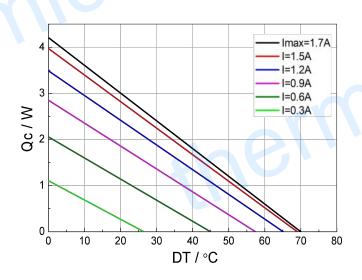
NS: No sealing AlO: Alumina white 96%

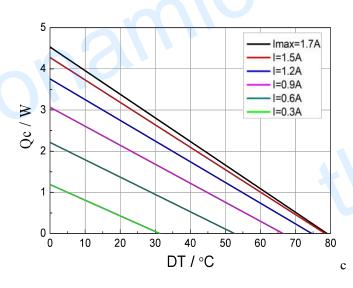
# **Specification of Thermoelectric Module**

### **TES1-03115**

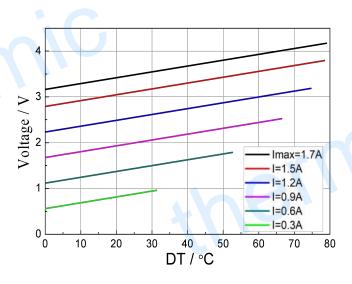
#### Performance Curves at Th=27 °C

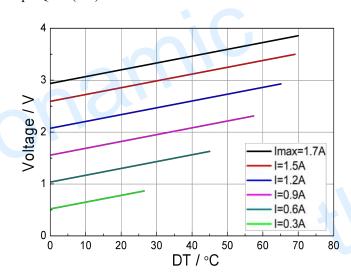
### Performance Curves at Th=50 °C



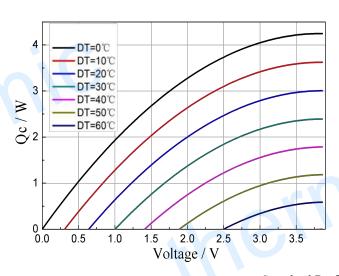


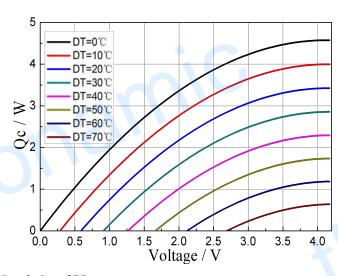
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V = f(DT)





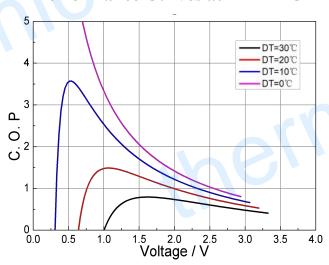
Standard Performance Graph Qc= f(V)

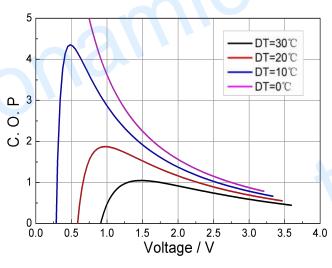
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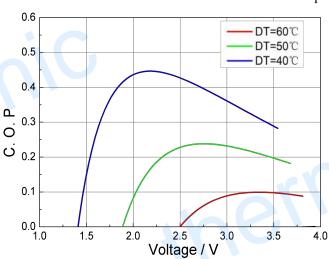


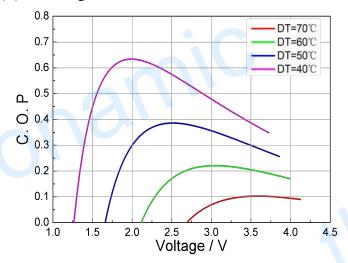
#### Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

# **Operation Caution**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.